

# **Chip Bonding Equipment Global Market Insights 2025, Analysis and Forecast to 2030, by Manufacturers, Regions, Technology, Application, Product Type**

<https://marketpublishers.com/r/C5D496DDE078EN.html>

Date: February 2025

Pages: 89

Price: US\$ 3,200.00 (Single User License)

ID: C5D496DDE078EN

## **Abstracts**

### **Chip Bonding Equipment Market Overview**

The chip bonding equipment market is experiencing significant growth as demand for advanced electronic devices in industries such as consumer electronics, automotive electronics, medical equipment, and aerospace continues to rise. Chip bonding is a crucial process in semiconductor packaging, enabling efficient and reliable connections between chips and substrates. As technology advances, chip bonding equipment is becoming increasingly sophisticated, supporting the development of smaller, faster, and more reliable electronic products. The market is projected to expand as automation and miniaturization trends continue to drive the demand for high-precision bonding solutions across various industries.

### **Market Size**

The global chip bonding equipment market is expected to grow at a compound annual growth rate (CAGR) of 7% to 12% during the forecast period. As the demand for consumer electronics and automotive electronics accelerates, the market is poised for substantial growth, particularly with the increased focus on high-performance chips used in mobile devices, electric vehicles, and medical devices. The expansion of industries such as aerospace and healthcare further supports the growth of chip bonding equipment, driven by the need for high-precision, durable bonding solutions.

### **Market Share & Trends Analysis**

#### **By Product Type**

The chip bonding equipment market is segmented into Die Bonders and Wire Bonders, each serving distinct needs within the semiconductor packaging process:

**Die Bonder:** Die bonders are expected to witness a strong demand due to their precision and capability to bond chips onto substrates. This segment is projected to grow at a CAGR of 8% to 11%, driven by the increasing need for high-performance semiconductors in mobile devices, automotive electronics, and medical equipment.

**Wire Bonder:** Wire bonders are anticipated to grow at a CAGR of 7% to 10%, as they offer cost-effective and reliable bonding solutions for a wide range of applications, especially in consumer electronics and automotive sectors. Their simplicity and efficiency in wire bonding make them a popular choice for mass production of electronic components.

### By Application

Chip bonding equipment is utilized in various applications, with each segment experiencing unique growth trends:

**Consumer Electronics:** The consumer electronics segment is expected to grow at a CAGR of 8% to 12%, fueled by the rising demand for mobile phones, wearables, and other smart devices. Chip bonding is critical for ensuring the reliable performance of these devices, driving the demand for advanced bonding equipment.

**Automotive Electronics:** The automotive electronics segment is projected to grow at a CAGR of 9% to 13%, driven by the increasing use of electronic components in electric vehicles, autonomous driving systems, and infotainment systems. This trend requires highly accurate and efficient bonding solutions to ensure the safety and performance of automotive electronics.

**Medical Equipment:** The medical equipment segment is anticipated to grow at a CAGR of 7% to 10%, as the demand for medical devices that incorporate high-performance chips continues to rise. Applications such as diagnostic equipment, patient monitoring devices, and wearable health tech rely on advanced chip bonding equipment for critical components.

**Aerospace:** The aerospace industry is expected to grow at a CAGR of 6% to 9%, with an increasing need for precision bonding solutions in avionics, satellite systems, and military electronics. Chip bonding in aerospace applications requires high reliability and durability, which is fueling demand for specialized bonding equipment.

### By Key Players

The key players in the chip bonding equipment market are renowned for their innovation in providing high-precision bonding solutions to meet the growing demands of the

semiconductor and electronics industries. Leading companies include:

**Besi:** Besi is a global leader in the design and manufacture of advanced chip bonding equipment. They offer a comprehensive range of die bonders and wire bonders that cater to various industries, including consumer electronics, automotive, medical, and aerospace. Besi is known for its cutting-edge technologies and innovation in bonding equipment.

**ASM Pacific Technology:** ASM Pacific Technology is a key player in the semiconductor equipment market, offering a range of die bonders and wire bonders designed to meet the high-performance demands of the electronics industry. Their bonding systems are widely used in the automotive and consumer electronics sectors.

**Kulicke and Soffa Industries:** Kulicke and Soffa is a major provider of chip bonding equipment with a strong focus on die bonding and wire bonding technologies. Their products are used extensively in consumer electronics, automotive electronics, and medical devices, supporting the production of advanced semiconductor packages.

**Shinkawa:** Shinkawa specializes in precision bonding technologies, providing die bonding and wire bonding solutions for a wide range of applications. Their products are particularly known for their high-quality performance in the consumer electronics and automotive industries.

**Palomar Technologies:** Palomar Technologies provides innovative chip bonding solutions, including die bonders and wire bonders, for industries such as medical devices, aerospace, and automotive electronics. Their equipment is known for its reliability and precision in bonding operations.

**Finetech:** Finetech offers advanced equipment for semiconductor packaging, including die bonders and wire bonders. Their products are used in industries such as medical electronics, aerospace, and consumer electronics, providing high-quality bonding solutions for various applications.

**EV Group:** EV Group is a leading provider of wafer bonding and die bonding equipment, with a strong presence in the semiconductor and electronics industries. Their advanced equipment is utilized in applications such as consumer electronics, automotive electronics, and medical devices.

**Dr. Tresky AG:** Dr. Tresky is known for providing high-precision die bonding and wire bonding systems used in semiconductor packaging. Their equipment is widely used in industries such as medical devices, aerospace, and consumer electronics.

**FiconTEC Service:** FiconTEC offers cutting-edge die bonding and wire bonding solutions for the semiconductor and electronics industries. Their products are tailored to meet the needs of high-performance applications in consumer electronics, automotive, and aerospace.

**InduBond:** InduBond specializes in advanced bonding equipment for the semiconductor

industry, offering die bonders and wire bonders for applications in consumer electronics, automotive, and medical equipment.

**DIAS Automation:** DIAS Automation provides innovative chip bonding equipment for the semiconductor market, offering solutions that meet the precise bonding needs of industries such as automotive, aerospace, and medical electronics.

**Hesse Mechatronics:** Hesse Mechatronics is a leading supplier of bonding equipment, including die bonders and wire bonders. Their systems are used in a variety of industries, including consumer electronics, automotive, and aerospace, where precision and reliability are crucial.

### By Region

The chip bonding equipment market is segmented into several key regions, each with unique growth dynamics:

**North America:** North America is expected to hold a market share of 30% to 35% and is projected to grow at a CAGR of 8% to 12%, driven by the demand for high-performance chips in automotive, aerospace, and medical devices.

**Europe:** Europe is expected to account for 25% to 30% of the market and grow at a CAGR of 7% to 10%, supported by robust demand in the automotive and aerospace industries.

**Asia-Pacific:** The Asia-Pacific region is expected to be the fastest-growing region, with a CAGR of 9% to 14%, driven by the booming semiconductor manufacturing industry in countries such as China, Japan, and South Korea.

**Latin America:** Latin America is forecasted to grow at a CAGR of 6% to 8%, with increasing demand for chip bonding solutions in the automotive and consumer electronics sectors.

**Middle East & Africa:** The Middle East & Africa region is expected to grow at a CAGR of 5% to 7%, supported by increased adoption of advanced technologies in automotive and aerospace industries.

### Segment Forecasts (2025-2030)

#### Growth in Key Segments

**Die Bonder:** The die bonder segment is expected to grow at a CAGR of 8% to 11%, driven by the increasing demand for high-performance and miniaturized chips in various applications.

**Wire Bonder:** The wire bonder segment is projected to grow at a CAGR of 7% to 10%, as wire bonding remains a key technology in the production of cost-effective and reliable semiconductor packages.

### Regional Insights

The Asia-Pacific region is expected to experience the highest

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